

Morning Tutorial

Final Program

HOT Chips 15

A Symposium on High-Performance Chips – August 17-19, 2003 Memorial Auditorium, Stanford University, Palo Alto, CA

Sunday, August 17, 2003

Chair: Tadao Nakamura

Test and Reliability Techniques for Robust System Designs Subhasish Mitra Intel

High quality and reliability of integrated circuits are keys to the design of robust systems using these parts. Hence, quality and reliability are rapidly becoming "features" just like performance, powerconsumption and die size, for both computing and communication applications. Economic analysis shows that it is infeasible to achieve the high levels of quality and reliability expected by customers without designing in these features from very early stages of product development. Techniques for designing quality and reliability features will be described and the associated future challenges will be discussed.

The tutorial will include discussions on the cost of quality, manufacturing defects and test methodologies, design for testability, test pattern generation, built-in-self-test, infant mortality of integrated circuits, impact of noise on test and reliability, soft errors, design techniques for soft error protection, concurrent error detection and self-repairing systems. Examples from actual products will be used to illustrate the applicability of these techniques.

Subhasish Mitra is a Senior Staff Engineer at Intel where he works Design for Testability, Reliability, Manufacturability and Debug. He is also a Consulting Assistant Professor in Stanford University's EE Department. Previously, he was the leader of the DARPA-sponsored ROAR (Reliability Obtained by Adaptive Reconfiguration) project at Stanford, and a consultant for Agilent's System Chip Testing project. His research interests include digital testing, fault-tolerant computing, VLSI design and computer architecture. His recent awards includea Recognition Award at Intel for developing a break-through compaction methodology for test cost reduction, and a Best Panel Award at the VLSI Test Symposium.

12:00-1:30 Lunch

8:30-12:00

1:30-5:00 Afternoon Tutorial Past and Future of Cryptographic Engineering Christof Paar

Chair: John Wawrzynek

Ruhr-Universitaet Bochum

Security has quickly evolved from a rather obscure niche area to an important aspect of today's IT applications. The recent trend of pervasive computing will make it necessary to integrate security functionality in an extremely broad spectrum of applications, from traditional computers to household appliances. This application range will force many engineers (without training in cryptography) to think about efficient ways of implementing crypto functions, which are the core tools for providing IT security.

This talk will give an overview of the field of IT security, with a strong focus on cryptographic engineering. After discussing the general objectives of IT security, we will introduce the types of practical crypto schemes, case studies that highlight both symmetric and asymmetric (public-key) algorithms and the challenges of implementing them in hardware and software, the architecture of a high performance public-key engine along with the interaction between implementation and security requirements, and an introduction to side channel attacks (perhaps the most important attacks against crypto schemes in the real world). The presentation will conclude with a discussion of future research challenges.

Christof Paar has the chair for Communication Security (www.crypto.rub.de/index_eng.html) at the Horst Gortz Institute for IT Security at the University of Bochum in Germany. As faculty member at Worcester Polytechnic Institute, he founded the Cryptography and Information Security Labs and is cofounder of the CHES (Cryptographic Hardware and Embedded Systems, www.chesworkshop.org) Workshop series. He has received an NSF CAREER award for research in cryptography and reconfigurable hardware. Christof Paar has been teaching cryptography courses in academia and industry since 1995.

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The HOT Chips I 5 symposium is sponsored by the Technical Committee on Microprocessors and Microcomputers of the IEEE Computer Society



5:00-6:00 Wine and Cheese Reception

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Monday, August 18, 2003

Tuesday, August 19, 2003

8:45- 9:00	Welcome, Opening RemarksGeneral Chair:Siamak AryaProgram Co-Chairs:Pradeep Dubey,Mike Flynn			
9:00-10:30	Session I: Supercomputing Session Chair: John Sell	9:00-10:30	Session 5: Switchi Session Chair:	ng and Routing Marc Tremblay
• Red Ste bandw • Quadrie Fabrizie Moray • Sub-lith André	orm: A 10,000 node system with reliable, high ridth, low latency interconnect Bob Alverson Cray cs QsNet II : A Network for Supercomputing Applications o Petrini, David Addison, Jon Beecroft, David Hewson, McLaren Los Alamos nographic Semiconductor Computing Systems DeHon Caltech	• A Single Takeshi Takashi • Terabit Uri Cur • Adaptiv Bill Lyn	e Chip Shared Mem Switt Shimizu, Yukihiro Nakagaw Miyoshi, Takeshi Horie, Ak Crossbar Switch Core mmings ve Packet Processor ch	tch w/ Twelve 10Gb Ethernet Ports va, Sridhar Pathi, Yasushi Umezawa, kira Hattori Fujitsu for Multi-Clock-Domain SoCs Fulcrum Procket
10:30-10:55	Break	10:30-11:00	Break	
10:55-11:45	Keynote: Chair: Mike Flynn	11:00-12:30	Session 6: Securit	y Pradeen Dubey
•The Wh	Iadashi Watanabe Vice President, High Performance Computing NEC Data Earth Simulator: World's Eastest Supercomputer	• Multi-G	Sigabit SSL & TLS Reco	ord Layer Protocol Processor
11:45-12:45 Session 2: Embedded		David Chin, Terry Tham • Continuum Security Processor: Micro-Architecture Overview		
	Session Chair: Howard Sachs	Srinivas	Mantripragada	NetContinuum
• A Multi Erik No • Intellig ARM9	threaded RISC/DSP Proc. w/ High Speed Interconnect borden Infineon ent Energy Management: an SoC Design Based on 26EI-S David Flynn ARM	• Nitrox- M. Ragł	II™ Inline Security Pro nib Hussain	ocessor Cavium
12:45- 2:00	Lunch	12:30- 1:45	Lunch	
2:00- 3:30	Session 3: Application Specific Chips	1:45- 2:35	Keynote:	Chair:Alan Smith
 Session Chair: Henry Moreton RAMP-IV: A Low-Power /High-Performance 2D/3D Graphics Accelerator for Mobile Multimedia Applications Ramchan Woo, Sungdae Choi, Ju-Ho Sohn, Seong-Jun Song, Young-Don Bae, and Hoi-Jun Yo KAIST TMS320DM310: A Portable Digital Media Processor Deepu Talla, Russ Austen, Dave Brier, Ching-Yu Hung, Derek Huynh, David Smith, Bruce Xiong, Raj Talluri, and Frank Brill Texas Instruments 		• Perspec 2:35- 2:45 2:45- 4:15 • Ubicon	Robert F. Leheny tives on the Future of Mi Short Break Session 7: Potpour Session Chair: n MASI - Wireless Netw	Director - Microsystems Technology Office DARPA icroelectronics for Military Systems rri Forest Baskett work Processor
ReX:A dNTSC Receiver System on Chip Slobodan Simovich Dotcast		• A 10 Gbps Ethernet TCP/IP Processor		
3:30- 4:00	Break	Jianping Xu, Nitin Borkar, Vasantha Erraguntla, Yatin Hoskote, Ianay Karnik, Sriram Vangal, Justin Batthar		
4:00- 6:00	Session 4: Wireless Session Chair: Keith Diefendorff	• Janus: A Gigaflop VLIW+RISC SoC Tile		SoCTile
• The Ar	chitecture of the Intel® PXA800F Cellular Processor		Rrock	Auner
Dilip K • BCM21 EDGE	 arishnaswamy 32: GSM/GPRS Handset Baseband w/ Integrated Media Functions 	4:30- 6:30	Session 8: Process Session Chair:	sors John Crawford
Nelson Sollenberger, Li Fung Chang, Paul Lu Broadcom • Broadcom WLAN chipset for 802.11 a/b/g Jason A. Trachewsky, Arya Behzad, Reza Rofougaran Broadcom		An Embedded 600Mhz Synthesized Processor Howard Sachs Telairity POWER5: IBM's Next Generation POWER Microprocessor Bon Kalla		
A UMTS Baseband Receiver Chip for Infrastructure Applications Sundararajan Sriram, K. Brown, P. Bertrand, F. Moerman, O. Paviot, C. Sengupta, V. Sundararajan, A. Gatherer Texas Instruments		• Ultrasp Sanjiv k	barc Gemini: Dual CPU Kapil	Processor Sun
6:00- 7:15	Dinner	Harry I	Muljono, Stefan Rusu	Intel
7:15-8:45	Panel: Disasters I Have Been Involved With	6:30- 6:45	Closing Remarks	
Moder Paneli:	rator: Nick Tredennick, Editor, Gilder Technology Report sts: Bob Cousins, CTO, Storfinity Dave Wyland, The Wyland Group, Inc. Jack D. Grimes, Consultant Jim Turley, Editor, Silicon-Insider			

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